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PATENT

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re application of: Cheng et al.

Application No. 10/749,283

Filed: December 30, 2003

Confirmation No. 9850

For: BUILT-IN SELF-ANALYZER FOR
EMBEDDED MEMORY

Examiner:

Art Unit: 2133

Attorney Reference No. 1011-66273-01

CERTIFICATE OF MAILING

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Attorney
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3/16/05

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PURSUANT TO 37 C.F.R. § 1.97(b)(3)**

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Listed on the accompanying form PTO-1449 and enclosed herewith are several English-language documents. Applicants respectfully request that these documents be listed as references cited on the issued patent.

If the present application was filed after June 30, 2003, copies of United States patents and United States published patent applications do not have to be provided to the Patent Office. This requirement of 37 C.F.R. § 1.98(a)(2)(i) has been waived by the United States Patent and Trademark Office pursuant to the Official Gazette Notice on August 5, 2003 (1276 OG 55). Applicants will provide copies of such patents upon request.

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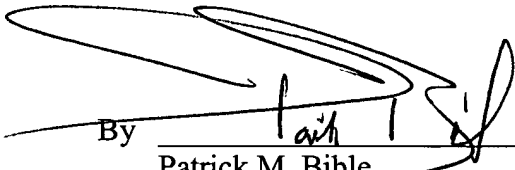
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The filing of this IDS shall not be construed to be an admission that the information cited in the statement is, or is considered to be, prior art or otherwise material to patentability as defined in 37 C.F.R. §1.56.

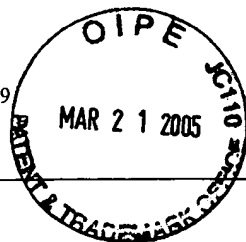
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INFORMATION DISCLOSURE STATEMENT BY APPLICANT

Attorney Docket Number 1011-66273-01

Application Number 10/749,283

Filing Date December 30, 2003

First Named Inventor Cheng

Art Unit 2133

Examiner Name

**Examiner's
Initials***

**Cite No.
(optional)**

OTHER DOCUMENTS

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**EXAMINER
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**DATE
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* Examiner: Initial if reference considered, whether or not in conformance with MPEP 609. Draw line through cite if not in conformance and not considered. Include copy of this form with next communication to applicant.